

## SNx4AC04 Hex Inverters

### 1 Features

- $V_{CC}$  operation of 2V to 6V
- Inputs accept voltages to 6V
- Max  $t_{pd}$  of 7ns at 5V

### 2 Applications

- [Synchronize inverted clock inputs](#)
- [Debounce a switch](#)
- Invert a digital signal

### 3 Description

The 'AC04 devices contain six independent inverters. The devices perform the Boolean function  $Y = \bar{A}$ .

#### Device Information

| PART NUMBER | PACKAGE <sup>(1)</sup> | PACKAGE SIZE <sup>(2)</sup> | BODY SIZE <sup>(3)</sup> |
|-------------|------------------------|-----------------------------|--------------------------|
| SNx4AC04    | BQA (WQFN, 14)         | 3mm x 2.5mm                 | 3mm x 2.5mm              |
|             | DB (SSOP, 14)          | 6.2mm x 7.8mm               | 6.2mm x 5.3mm            |
|             | D (SOIC, 14)           | 8.65mm x 6mm                | 8.65mm x 3.9mm           |
|             | NS (SOP, 14)           | 10.2mm x 7.8mm              | 10.3mm x 5.3mm           |
|             | PW (TSSOP, 14)         | 5mm x 6.4mm                 | 5mm x 4.4mm              |

- (1) For more information, see [Mechanical, Packaging, and Orderable Information](#).
- (2) The package size (length x width) is a nominal value and includes pins, where applicable.
- (3) The body size (length x width) is a nominal value and does not include pins.



Logic Diagram (Positive Logic)



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## 4 Pin Configuration and Functions

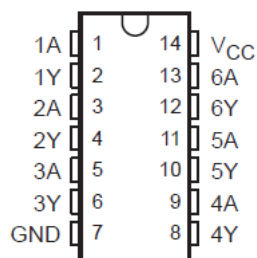


**Figure 4-1. SN54AC04 J or W Package; SN74AC04 D, DB, N, NS, or PW Package; 14-Pin CDIP, CFP, SOIC, SSOP, PDIP, SOP, and TSSOP (Top View)**

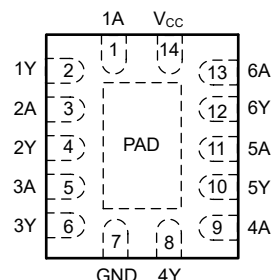


**Figure 4-2. SN74AC04 BQA Package, 14-Pin WQFN (Top View)**

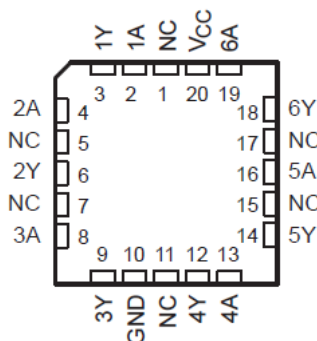


**Figure 4-3. SN54AC04 FK Package, 20-Pin LCCC (Top View)**

| NAME                       | PIN                            |                     | I/O    | DESCRIPTION                                                                                             |
|----------------------------|--------------------------------|---------------------|--------|---------------------------------------------------------------------------------------------------------|
|                            | D, DB, N, NS, PW, J, W, or BQA | FK                  |        |                                                                                                         |
| 1A                         | 1                              | 2                   | Input  | Channel 1, Input A                                                                                      |
| 1Y                         | 2                              | 3                   | Output | Channel 1, Output Y                                                                                     |
| 2A                         | 3                              | 4                   | Input  | Channel 2, Input A                                                                                      |
| 2Y                         | 4                              | 6                   | Output | Channel 2, Output Y                                                                                     |
| 3A                         | 5                              | 8                   | Input  | Channel 3, Input A                                                                                      |
| 3Y                         | 6                              | 9                   | Output | Channel 3, Output Y                                                                                     |
| GND                        | 7                              | 10                  | —      | Ground                                                                                                  |
| 4Y                         | 8                              | 12                  | Output | Channel 4, Output Y                                                                                     |
| 4A                         | 9                              | 13                  | Input  | Channel 4, Input A                                                                                      |
| 5Y                         | 10                             | 14                  | Output | Channel 5, Output Y                                                                                     |
| 5A                         | 11                             | 16                  | Input  | Channel 5, Input A                                                                                      |
| 6Y                         | 12                             | 18                  | Output | Channel 6, Output Y                                                                                     |
| 6A                         | 13                             | 19                  | Input  | Channel 6, Input A                                                                                      |
| V <sub>CC</sub>            | 14                             | 20                  | —      | Positive Supply                                                                                         |
| NC                         |                                | 1, 5, 7, 11, 15, 17 | —      | Not internally connected                                                                                |
| Thermal Pad <sup>(1)</sup> |                                |                     | —      | The thermal pad can be connected to GND or left floating. Do not connect to any other signal or supply. |

(1) BQA package only.

## 5 Specifications

### 5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

|           |                                            | MIN                         | MAX            | UNIT    |
|-----------|--------------------------------------------|-----------------------------|----------------|---------|
| $V_{CC}$  | Supply voltage range                       | −0.5                        | 7              | V       |
| $V_I$     | Input voltage range <sup>(2)</sup>         | −0.5                        | $V_{CC} + 0.5$ | V       |
| $V_O$     | Output voltage range <sup>(2)</sup>        | −0.5                        | $V_{CC} + 0.5$ | V       |
| $I_{IK}$  | Input clamp current                        | $V_I < 0$ or $V_I > V_{CC}$ |                | ±20 mA  |
| $I_{OK}$  | Output clamp current                       | $V_O < 0$ or $V_O > V_{CC}$ |                | ±20 mA  |
| $I_O$     | Continuous output current                  | $V_O = 0$ to $V_{CC}$       |                | ±50 mA  |
|           | Continuous current through $V_{CC}$ or GND |                             |                | ±200 mA |
| $T_{stg}$ | Storage temperature range                  | −60                         | 150            | °C      |

(1) Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

### 5.2 ESD Ratings

|             |                         | VALUE                                                                          | UNIT  |
|-------------|-------------------------|--------------------------------------------------------------------------------|-------|
| $V_{(ESD)}$ | Electrostatic discharge | Human body model (HBM), per ANSI/ESDA/JEDEC JS-001 <sup>(1)</sup>              | ±3000 |
|             |                         | Charged-device model (CDM), per JEDEC specification JESD22-C101 <sup>(2)</sup> | ±1000 |

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

### 5.3 Recommended Operating Conditions

over recommended operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

|                     |                                    |                         | SN54AC04 |          | SN74AC04 |          | UNIT |
|---------------------|------------------------------------|-------------------------|----------|----------|----------|----------|------|
|                     |                                    |                         | MIN      | MAX      | MIN      | MAX      |      |
| $V_{CC}$            | Supply voltage                     |                         | 2        | 6        | 2        | 6        | V    |
| $V_{IH}$            | High-level input voltage           | $V_{CC} = 3\text{ V}$   | 2.1      |          | 2.1      |          | V    |
|                     |                                    | $V_{CC} = 4.5\text{ V}$ | 3.15     |          | 3.15     |          |      |
|                     |                                    | $V_{CC} = 5.5\text{ V}$ | 3.85     |          | 3.85     |          |      |
| $V_{IL}$            | Low-level input voltage            | $V_{CC} = 3\text{ V}$   |          | 0.9      |          | 0.9      | V    |
|                     |                                    | $V_{CC} = 4.5\text{ V}$ |          | 1.35     |          | 1.35     |      |
|                     |                                    | $V_{CC} = 5.5\text{ V}$ |          | 1.65     |          | 1.65     |      |
| $V_I$               | Input voltage                      |                         | 0        | $V_{CC}$ | 0        | $V_{CC}$ | V    |
| $V_O$               | Output voltage                     |                         | 0        | $V_{CC}$ | 0        | $V_{CC}$ | V    |
| $I_{OH}$            | High-level output current          | $V_{CC} = 3\text{ V}$   |          | −12      |          | −12      | mA   |
|                     |                                    | $V_{CC} = 4.5\text{ V}$ |          | −24      |          | −24      |      |
|                     |                                    | $V_{CC} = 5.5\text{ V}$ |          | −24      |          | −24      |      |
| $I_{OL}$            | Low-level output current           | $V_{CC} = 3\text{ V}$   |          | 12       |          | 12       | mA   |
|                     |                                    | $V_{CC} = 4.5\text{ V}$ |          | 24       |          | 24       |      |
|                     |                                    | $V_{CC} = 5.5\text{ V}$ |          | 24       |          | 24       |      |
| $\Delta t/\Delta v$ | Input transition rise or fall rate |                         |          | 8        |          | 8        | ns/V |
| $T_A$               | Operating free-air temperature     |                         | −55      | 125      | −40      | 85       | °C   |

(1) All unused inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number [SCBA004](#).

## 5.4 Thermal Information

| THERMAL METRIC <sup>(1)</sup> |                                        | SN74AC04      |             |              |             |             |               | UNIT |
|-------------------------------|----------------------------------------|---------------|-------------|--------------|-------------|-------------|---------------|------|
|                               |                                        | BQA<br>(WQFN) | D<br>(SOIC) | DB<br>(SSOP) | N<br>(PDIP) | NS<br>(SOP) | PW<br>(TSSOP) |      |
|                               |                                        | 14 PINS       |             |              |             |             |               |      |
| R <sub>θJA</sub>              | Junction-to-ambient thermal resistance | 93.4          | 89.9        | 96           | 80          | 92.4        | 148           | °C/W |

(1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report, [SPRA953](#).

## 5.5 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER       | TEST CONDITIONS                                             | V <sub>CC</sub> | T <sub>A</sub> = 25°C |       |      | SN54AC04 |      | SN74AC04 |      | UNIT |
|-----------------|-------------------------------------------------------------|-----------------|-----------------------|-------|------|----------|------|----------|------|------|
|                 |                                                             |                 | MIN                   | TYP   | MAX  | MIN      | MAX  | MIN      | MAX  |      |
| V <sub>OH</sub> | I <sub>OH</sub> = –50 μA                                    | 3 V             | 2.9                   | 2.99  |      | 2.9      |      | 2.9      |      | V    |
|                 |                                                             | 4.5 V           | 4.4                   | 4.49  |      | 4.4      |      | 4.4      |      |      |
|                 |                                                             | 5.5 V           | 5.4                   | 5.49  |      | 5.4      |      | 5.4      |      |      |
|                 | I <sub>OH</sub> = –12 mA                                    | 3 V             | 2.56                  |       |      | 2.4      |      | 2.46     |      |      |
|                 | I <sub>OH</sub> = –24 mA                                    | 4.5 V           | 3.86                  |       |      | 3.7      |      | 3.76     |      |      |
|                 |                                                             | 5.5 V           | 4.86                  |       |      | 4.7      |      | 4.76     |      |      |
|                 | I <sub>OH</sub> = –50 mA <sup>(1)</sup>                     | 5.5 V           |                       |       |      | 3.85     |      |          |      |      |
| V <sub>OL</sub> | I <sub>OL</sub> = 50 μA                                     | 3 V             |                       | 0.002 | 0.1  |          | 0.1  |          | 0.1  | V    |
|                 |                                                             | 4.5 V           |                       | 0.001 | 0.1  |          | 0.1  |          | 0.1  |      |
|                 |                                                             | 5.5 V           |                       | 0.001 | 0.1  |          | 0.1  |          | 0.1  |      |
|                 | I <sub>OL</sub> = 12 mA                                     | 3 V             |                       |       | 0.36 |          | 0.5  |          | 0.44 |      |
|                 | I <sub>OL</sub> = 24 mA                                     | 4.5 V           |                       |       | 0.36 |          | 0.5  |          | 0.44 |      |
|                 |                                                             | 5.5 V           |                       |       | 0.36 |          | 0.5  |          | 0.44 |      |
|                 | I <sub>OL</sub> = 50 mA <sup>(1)</sup>                      | 5.5 V           |                       |       |      |          | 1.65 |          |      |      |
| I <sub>I</sub>  | V <sub>I</sub> = V <sub>CC</sub> or GND, I <sub>O</sub> = 0 | 5.5 V           |                       |       | ±0.1 |          | ±1   |          | ±1   | μA   |
|                 |                                                             | 5.5 V           |                       |       | 2    |          | 40   |          | 20   |      |
| C <sub>i</sub>  | V <sub>I</sub> = V <sub>CC</sub> or GND                     |                 |                       | 2.8   |      |          |      |          |      | pF   |

(1) Not more than one output should be tested at a time, and the duration of the test should not exceed 2 ms.

## 5.6 Switching Characteristics

over recommended operating free-air temperature range, V<sub>CC</sub> = 3.3 V ± 0.3 V (unless otherwise noted) (see [Load Circuit and Voltage Waveforms](#) )

| PARAMETER        | FROM<br>(INPUT) | TO<br>(OUTPUT) | T <sub>A</sub> = 25°C |     |     | SN54AC04 |     | SN74AC04 |     | UNIT |
|------------------|-----------------|----------------|-----------------------|-----|-----|----------|-----|----------|-----|------|
|                  |                 |                | MIN                   | TYP | MAX | MIN      | MAX | MIN      | MAX |      |
| t <sub>PLH</sub> | A               | Y              | 1.5                   | 4.5 | 9   | 1        | 11  | 1        | 10  | ns   |
| t <sub>PHL</sub> |                 |                | 1.5                   | 4.5 | 8.5 | 1        | 10  | 1        | 9.5 |      |

## 5.7 Operating Characteristics

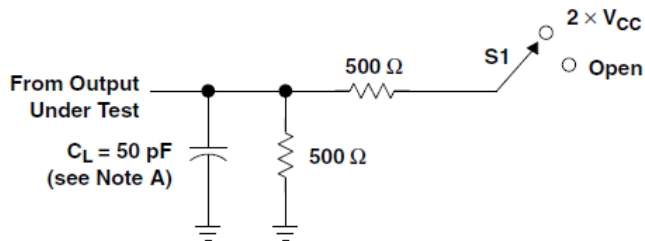
V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C

| PARAMETER                                     | TEST CONDITIONS                  | TYP | UNIT |
|-----------------------------------------------|----------------------------------|-----|------|
| C <sub>pd</sub> Power dissipation capacitance | C <sub>L</sub> = 50 pF f = 1 MHz | 45  | pF   |

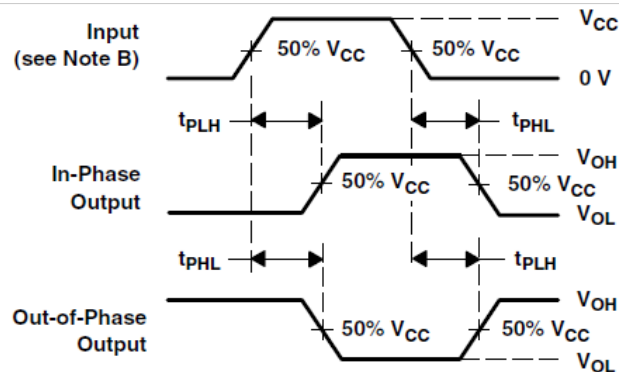
## 6 Parameter Measurement Information

### Load Circuit and Voltage Waveforms

| TEST              | S1   |
|-------------------|------|
| $t_{PLH}/t_{PHL}$ | Open |



LOAD CIRCUIT



VOLTAGE WAVEFORMS

- NOTES: A.  $C_L$  includes probe and jig capacitance.  
 B. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 1 \text{ MHz}$ ,  $Z_O = 50 \Omega$ ,  $t_r \leq 2.5 \text{ ns}$ ,  $t_f \leq 2.5 \text{ ns}$ .  
 C. The outputs are measured one at a time with one input transition per measurement.

## 7 Detailed Description

### 7.1 Overview

The 'AC04 devices contain six independent inverters. The devices perform the Boolean function  $Y = \bar{A}$ .

### 7.2 Functional Block Diagram



Logic Diagram (Positive Logic)

### 7.3 Feature Description

The SNx4AC04 devices have an operating  $V_{CC}$  range from 2 V to 6 V.

### 7.4 Device Functional Modes

Function Table lists the function modes of the SNx4ACT04.

Function Table  
(Each Inverter)

| INPUT | OUTPUT |
|-------|--------|
| A     | Y      |
| H     | L      |
| L     | H      |

## 8 Application and Implementation

### Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

### 8.1 Application Information

The SNx4ACT04 is a low-drive CMOS device that can be used for a multitude of bus interface type applications where output ringing is a concern. The low drive and slow edge rates will minimize overshoot and undershoot on the outputs.

### 8.2 Typical Application

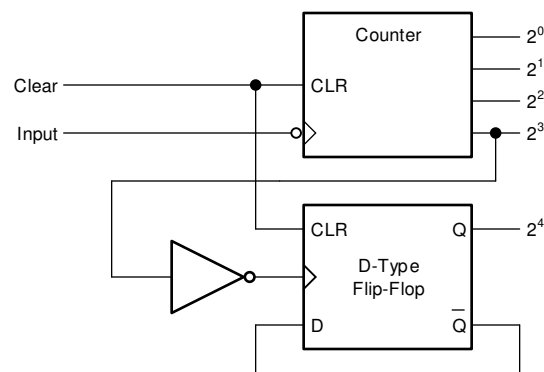


Figure 8-1. Typical Application Schematic

#### 8.2.1 Design Requirements

This device uses CMOS technology and has balanced output drive. Care should be taken to avoid bus contention because it can drive currents that would exceed maximum limits. Outputs can be combined to produce higher drive but the high drive will also create faster edges into light loads, so routing and load conditions should be considered to prevent ringing.

#### 8.2.2 Detailed Design Procedure

1. Recommended Input Conditions
  - Rise time and fall time specs: See ( $\Delta t/\Delta V$ ) in the [Section 5.3](#).
  - Specified high and low levels: See ( $V_{IH}$  and  $V_{IL}$ ) in the [Section 5.3](#).
2. Recommend Output Conditions
  - Load currents should not exceed 25 mA per output and 75 mA total for the part.
  - Outputs should not be pulled above  $V_{CC}$ .

### 8.2.3 Application Curve

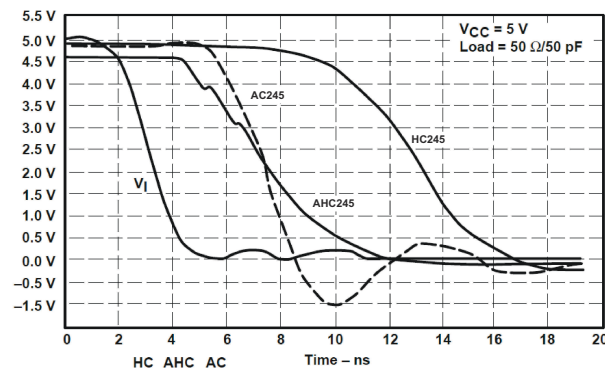


**Figure 8-2. Switching Characteristics Comparison**

## 8.3 Power Supply Recommendations

The power supply can be any voltage between the MIN and MAX supply voltage rating located in the [Section 5.3](#).

Each  $V_{CC}$  pin should have a good bypass capacitor to prevent power disturbance. For devices with a single supply, 0.1  $\mu\text{F}$  is recommended; if there are multiple  $V_{CC}$  pins, then 0.01  $\mu\text{F}$  or 0.022  $\mu\text{F}$  is recommended for each power pin. It is acceptable to parallel multiple bypass caps to reject different frequencies of noise. A 0.1  $\mu\text{F}$  and a 1  $\mu\text{F}$  are commonly used in parallel. The bypass capacitor should be installed as close to the power pin as possible for best results.

## 8.4 Layout

### 8.4.1 Layout Guidelines

When using multiple-bit logic devices, inputs should never float.

In many cases, functions or parts of functions of digital logic devices are unused, for example, when only two inputs of a triple-input AND gate are used or only 3 of the 4 buffer gates are used. Such input pins should not be left unconnected because the undefined voltages at the outside connections result in undefined operational states. [Section 8.4.1.1](#) specifies the rules that must be observed under all circumstances. All unused inputs of digital logic devices must be connected to a high or low bias to prevent them from floating. The logic level that should be applied to any particular unused input depends on the function of the device. Generally they will be tied to GND or  $V_{CC}$ , whichever makes more sense or is more convenient. It is generally acceptable to float outputs, unless the part is a transceiver. If the transceiver has an output enable pin, it will disable the output section of the part when asserted. This will not disable the input section of the IOs, so they cannot float when disabled.

#### 8.4.1.1 Layout Example

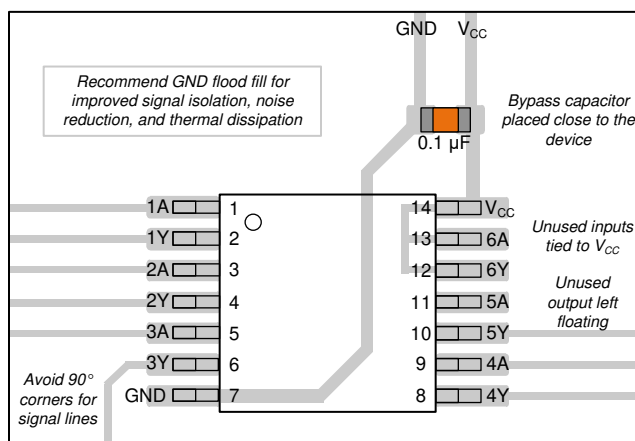


**Figure 8-3. Example Layout of the SN74AC04**

## 9 Device and Documentation Support

TI offers an extensive line of development tools. Tools and software to evaluate the performance of the device, generate code, and develop solutions are listed below.

### 9.1 Device and Documentation Support

#### 9.1.1 Related Documentation

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

**Table 9-1. Related Links**

| PARTS    | PRODUCT FOLDER             | SAMPLE & BUY               | TECHNICAL DOCUMENTS        | TOOLS & SOFTWARE           | SUPPORT & COMMUNITY        |
|----------|----------------------------|----------------------------|----------------------------|----------------------------|----------------------------|
| SN54AC04 | <a href="#">Click here</a> | <a href="#">Click here</a> | <a href="#">Click here</a> | <a href="#">Click here</a> | <a href="#">Click here</a> |
| SN74AC04 | <a href="#">Click here</a> | <a href="#">Click here</a> | <a href="#">Click here</a> | <a href="#">Click here</a> | <a href="#">Click here</a> |

### 9.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on [ti.com](#). Click on *Notifications* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

### 9.3 Support Resources

[TI E2E™ support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

### 9.4 Trademarks

TI E2E™ is a trademark of Texas Instruments.

All trademarks are the property of their respective owners.

### 9.5 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

### 9.6 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

## 10 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

| <b>Changes from Revision F (January 2023) to Revision G (July 2024)</b>                                                                           | <b>Page</b> |
|---------------------------------------------------------------------------------------------------------------------------------------------------|-------------|
| • Added BQA package to <i>Device Information</i> table, <i>Pin Configuration and Functions</i> section, and <i>Thermal Information</i> table..... | 1           |
| • Added package size to <i>Device Information</i> table.....                                                                                      | 1           |
| • Updated RθJA values: D = 86 to 89.9, NS = 76 to 92.4, PW = 113 to 148, all values in °C/W.....                                                  | 5           |
| • Updated <i>Layout Example</i> image.....                                                                                                        | 10          |

**Changes from Revision E (July 1995) to Revision F (January 2023)****Page**

- Added *Applications*, *Device Information* table, *Pin Functions* table, *ESD Ratings* table, *Thermal Information* table, *Typical Characteristics*, *Feature Description* section, *Device Functional Modes*, *Application and Implementation* section, *Power Supply Recommendations* section, *Layout* section, *Device and Documentation Support* section, and *Mechanical, Packaging, and Orderable Information* section..... 1

**11 Mechanical, Packaging, and Orderable Information**

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

**PACKAGING INFORMATION**

| Orderable part number          | Status<br>(1) | Material type<br>(2) | Package   Pins  | Package qty   Carrier | RoHS<br>(3) | Lead finish/<br>Ball material<br>(4) | MSL rating/<br>Peak reflow<br>(5) | Op temp (°C) | Part marking<br>(6)                   |
|--------------------------------|---------------|----------------------|-----------------|-----------------------|-------------|--------------------------------------|-----------------------------------|--------------|---------------------------------------|
| <a href="#">5962-87609012A</a> | Active        | Production           | LCCC (FK)   20  | 55   TUBE             | No          | SNPB                                 | N/A for Pkg Type                  | -55 to 125   | 5962-<br>87609012A<br>SNJ54AC<br>04FK |
| <a href="#">5962-8760901CA</a> | Active        | Production           | CDIP (J)   14   | 25   TUBE             | No          | SNPB                                 | N/A for Pkg Type                  | -55 to 125   | 5962-8760901CA<br>SNJ54AC04J          |
| <a href="#">5962-8760901DA</a> | Active        | Production           | CFP (W)   14    | 25   TUBE             | No          | SNPB                                 | N/A for Pkg Type                  | -55 to 125   | 5962-8760901DA<br>SNJ54AC04W          |
| <a href="#">SN74AC04BQAR</a>   | Active        | Production           | WQFN (BQA)   14 | 3000   LARGE T&R      | Yes         | NIPDAU                               | Level-1-260C-UNLIM                | -40 to 125   | AC04                                  |
| SN74AC04BQAR.A                 | Active        | Production           | WQFN (BQA)   14 | 3000   LARGE T&R      | Yes         | NIPDAU                               | Level-1-260C-UNLIM                | -40 to 125   | AC04                                  |
| <a href="#">SN74AC04D</a>      | Obsolete      | Production           | SOIC (D)   14   | -                     | -           | Call TI                              | Call TI                           | -40 to 85    | AC04                                  |
| <a href="#">SN74AC04DBR</a>    | Active        | Production           | SSOP (DB)   14  | 2000   LARGE T&R      | Yes         | NIPDAU                               | Level-1-260C-UNLIM                | -40 to 85    | AC04                                  |
| SN74AC04DBR.A                  | Active        | Production           | SSOP (DB)   14  | 2000   LARGE T&R      | Yes         | NIPDAU                               | Level-1-260C-UNLIM                | -40 to 125   | AC04                                  |
| <a href="#">SN74AC04DR</a>     | Active        | Production           | SOIC (D)   14   | 2500   LARGE T&R      | Yes         | NIPDAU   NIPDAU                      | Level-1-260C-UNLIM                | -40 to 85    | AC04                                  |
| SN74AC04DR.A                   | Active        | Production           | SOIC (D)   14   | 2500   LARGE T&R      | Yes         | NIPDAU                               | Level-1-260C-UNLIM                | -40 to 125   | AC04                                  |
| SN74AC04DRG4.A                 | Active        | Production           | SOIC (D)   14   | 2500   LARGE T&R      | Yes         | NIPDAU                               | Level-1-260C-UNLIM                | -40 to 125   | AC04                                  |
| <a href="#">SN74AC04N</a>      | Active        | Production           | PDIP (N)   14   | 25   TUBE             | Yes         | NIPDAU                               | N/A for Pkg Type                  | -40 to 85    | SN74AC04N                             |
| SN74AC04N.A                    | Active        | Production           | PDIP (N)   14   | 25   TUBE             | Yes         | NIPDAU                               | N/A for Pkg Type                  | -40 to 125   | SN74AC04N                             |
| SN74AC04NE4                    | Active        | Production           | PDIP (N)   14   | 25   TUBE             | Yes         | NIPDAU                               | N/A for Pkg Type                  | -40 to 85    | SN74AC04N                             |
| <a href="#">SN74AC04NSR</a>    | Active        | Production           | SOP (NS)   14   | 2000   LARGE T&R      | Yes         | NIPDAU   NIPDAU                      | Level-1-260C-UNLIM                | -40 to 85    | AC04                                  |
| SN74AC04NSR.A                  | Active        | Production           | SOP (NS)   14   | 2000   LARGE T&R      | Yes         | NIPDAU                               | Level-1-260C-UNLIM                | -40 to 125   | AC04                                  |
| <a href="#">SN74AC04PW</a>     | Obsolete      | Production           | TSSOP (PW)   14 | -                     | -           | Call TI                              | Call TI                           | -40 to 85    | AC04                                  |
| <a href="#">SN74AC04PWR</a>    | Active        | Production           | TSSOP (PW)   14 | 2000   LARGE T&R      | Yes         | NIPDAU   SN                          | Level-1-260C-UNLIM                | -40 to 85    | AC04                                  |
| SN74AC04PWR.A                  | Active        | Production           | TSSOP (PW)   14 | 2000   LARGE T&R      | Yes         | NIPDAU                               | Level-1-260C-UNLIM                | -40 to 125   | AC04                                  |
| <a href="#">SN74AC04PWRG4</a>  | Active        | Production           | TSSOP (PW)   14 | 2000   LARGE T&R      | Yes         | NIPDAU                               | Level-1-260C-UNLIM                | -40 to 85    | AC04                                  |
| SN74AC04PWRG4.A                | Active        | Production           | TSSOP (PW)   14 | 2000   LARGE T&R      | Yes         | NIPDAU                               | Level-1-260C-UNLIM                | -40 to 125   | AC04                                  |
| <a href="#">SNJ54AC04FK</a>    | Active        | Production           | LCCC (FK)   20  | 55   TUBE             | No          | SNPB                                 | N/A for Pkg Type                  | -55 to 125   | 5962-<br>87609012A<br>SNJ54AC<br>04FK |

| Orderable part number      | Status<br>(1) | Material type<br>(2) | Package   Pins | Package qty   Carrier | RoHS<br>(3) | Lead finish/<br>Ball material<br>(4) | MSL rating/<br>Peak reflow<br>(5) | Op temp (°C) | Part marking<br>(6)               |
|----------------------------|---------------|----------------------|----------------|-----------------------|-------------|--------------------------------------|-----------------------------------|--------------|-----------------------------------|
| SNJ54AC04FK.A              | Active        | Production           | LCCC (FK)   20 | 55   TUBE             | No          | SNPB                                 | N/A for Pkg Type                  | -55 to 125   | 5962-87609012A<br>SNJ54AC<br>04FK |
| <a href="#">SNJ54AC04J</a> | Active        | Production           | CDIP (J)   14  | 25   TUBE             | No          | SNPB                                 | N/A for Pkg Type                  | -55 to 125   | 5962-8760901CA<br>SNJ54AC04J      |
| SNJ54AC04J.A               | Active        | Production           | CDIP (J)   14  | 25   TUBE             | No          | SNPB                                 | N/A for Pkg Type                  | -55 to 125   | 5962-8760901CA<br>SNJ54AC04J      |
| <a href="#">SNJ54AC04W</a> | Active        | Production           | CFP (W)   14   | 25   TUBE             | No          | SNPB                                 | N/A for Pkg Type                  | -55 to 125   | 5962-8760901DA<br>SNJ54AC04W      |
| SNJ54AC04W.A               | Active        | Production           | CFP (W)   14   | 25   TUBE             | No          | SNPB                                 | N/A for Pkg Type                  | -55 to 125   | 5962-8760901DA<br>SNJ54AC04W      |

<sup>(1)</sup> **Status:** For more details on status, see our [product life cycle](#).

<sup>(2)</sup> **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

<sup>(4)</sup> **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

<sup>(6)</sup> **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

**Important Information and Disclaimer:**The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**OTHER QUALIFIED VERSIONS OF SN54AC04, SN74AC04 :**

- Catalog : [SN74AC04](#)
- Automotive : [SN74AC04-Q1](#), [SN74AC04-Q1](#)
- Enhanced Product : [SN74AC04-EP](#), [SN74AC04-EP](#)
- Military : [SN54AC04](#)

**NOTE: Qualified Version Definitions:**

- Catalog - TI's standard catalog product
- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Enhanced Product - Supports Defense, Aerospace and Medical Applications
- Military - QML certified for Military and Defense Applications

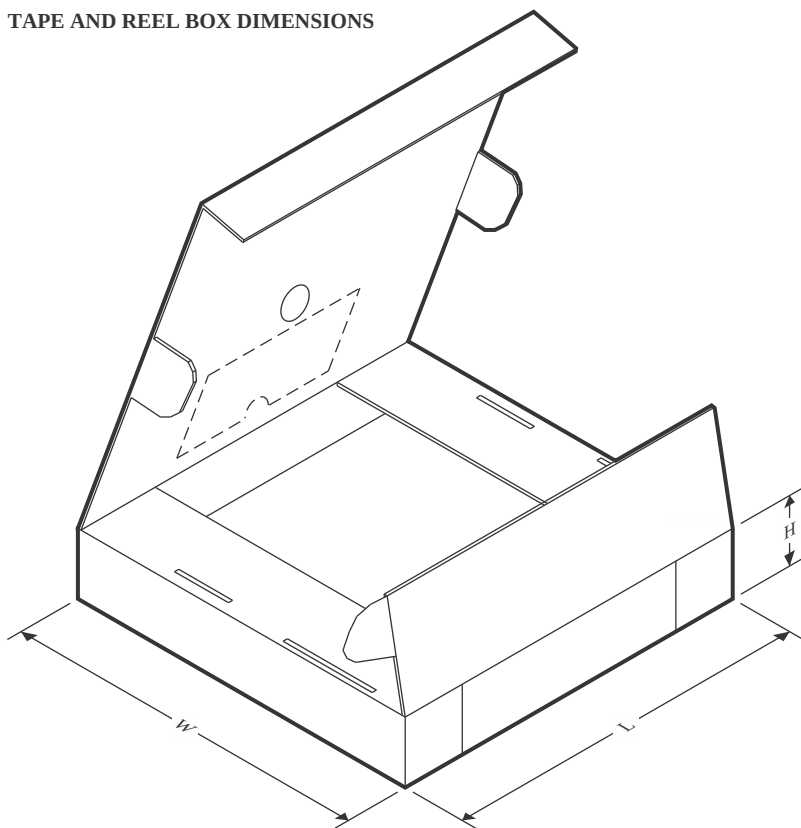
## TAPE AND REEL INFORMATION



\*All dimensions are nominal

| Device        | Package Type | Package Drawing | Pins | SPQ  | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|---------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| SN74AC04BQAR  | WQFN         | BQA             | 14   | 3000 | 180.0              | 12.4               | 2.8     | 3.3     | 1.1     | 4.0     | 12.0   | Q1            |
| SN74AC04DBR   | SSOP         | DB              | 14   | 2000 | 330.0              | 16.4               | 8.35    | 6.6     | 2.4     | 12.0    | 16.0   | Q1            |
| SN74AC04DR    | SOIC         | D               | 14   | 2500 | 330.0              | 16.4               | 6.5     | 9.0     | 2.1     | 8.0     | 16.0   | Q1            |
| SN74AC04DR    | SOIC         | D               | 14   | 2500 | 330.0              | 12.4               | 3.75    | 3.75    | 1.15    | 8.0     | 12.0   | Q1            |
| SN74AC04DR    | SOIC         | D               | 14   | 2500 | 330.0              | 16.4               | 6.5     | 9.0     | 2.1     | 8.0     | 16.0   | Q1            |
| SN74AC04NSR   | SOP          | NS              | 14   | 2000 | 330.0              | 16.4               | 8.1     | 10.4    | 2.5     | 12.0    | 16.0   | Q1            |
| SN74AC04NSR   | SOP          | NS              | 14   | 2000 | 330.0              | 16.4               | 8.45    | 10.55   | 2.5     | 12.0    | 16.2   | Q1            |
| SN74AC04PWR   | TSSOP        | PW              | 14   | 2000 | 330.0              | 12.4               | 6.9     | 5.6     | 1.6     | 8.0     | 12.0   | Q1            |
| SN74AC04PWR   | TSSOP        | PW              | 14   | 2000 | 330.0              | 12.4               | 6.9     | 5.6     | 1.6     | 8.0     | 12.0   | Q1            |
| SN74AC04PWRG4 | TSSOP        | PW              | 14   | 2000 | 330.0              | 12.4               | 6.9     | 5.6     | 1.6     | 8.0     | 12.0   | Q1            |
| SN74AC04PWRG4 | TSSOP        | PW              | 14   | 2000 | 330.0              | 12.4               | 6.9     | 5.6     | 1.6     | 8.0     | 12.0   | Q1            |

## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

| Device        | Package Type | Package Drawing | Pins | SPQ  | Length (mm) | Width (mm) | Height (mm) |
|---------------|--------------|-----------------|------|------|-------------|------------|-------------|
| SN74AC04BQAR  | WQFN         | BQA             | 14   | 3000 | 210.0       | 185.0      | 35.0        |
| SN74AC04DBR   | SSOP         | DB              | 14   | 2000 | 356.0       | 356.0      | 35.0        |
| SN74AC04DR    | SOIC         | D               | 14   | 2500 | 356.0       | 356.0      | 35.0        |
| SN74AC04DR    | SOIC         | D               | 14   | 2500 | 340.5       | 336.1      | 32.0        |
| SN74AC04DR    | SOIC         | D               | 14   | 2500 | 353.0       | 353.0      | 32.0        |
| SN74AC04NSR   | SOP          | NS              | 14   | 2000 | 367.0       | 367.0      | 38.0        |
| SN74AC04NSR   | SOP          | NS              | 14   | 2000 | 353.0       | 353.0      | 32.0        |
| SN74AC04PWR   | TSSOP        | PW              | 14   | 2000 | 356.0       | 356.0      | 35.0        |
| SN74AC04PWR   | TSSOP        | PW              | 14   | 2000 | 353.0       | 353.0      | 32.0        |
| SN74AC04PWRG4 | TSSOP        | PW              | 14   | 2000 | 356.0       | 356.0      | 35.0        |
| SN74AC04PWRG4 | TSSOP        | PW              | 14   | 2000 | 353.0       | 353.0      | 32.0        |

## TUBE

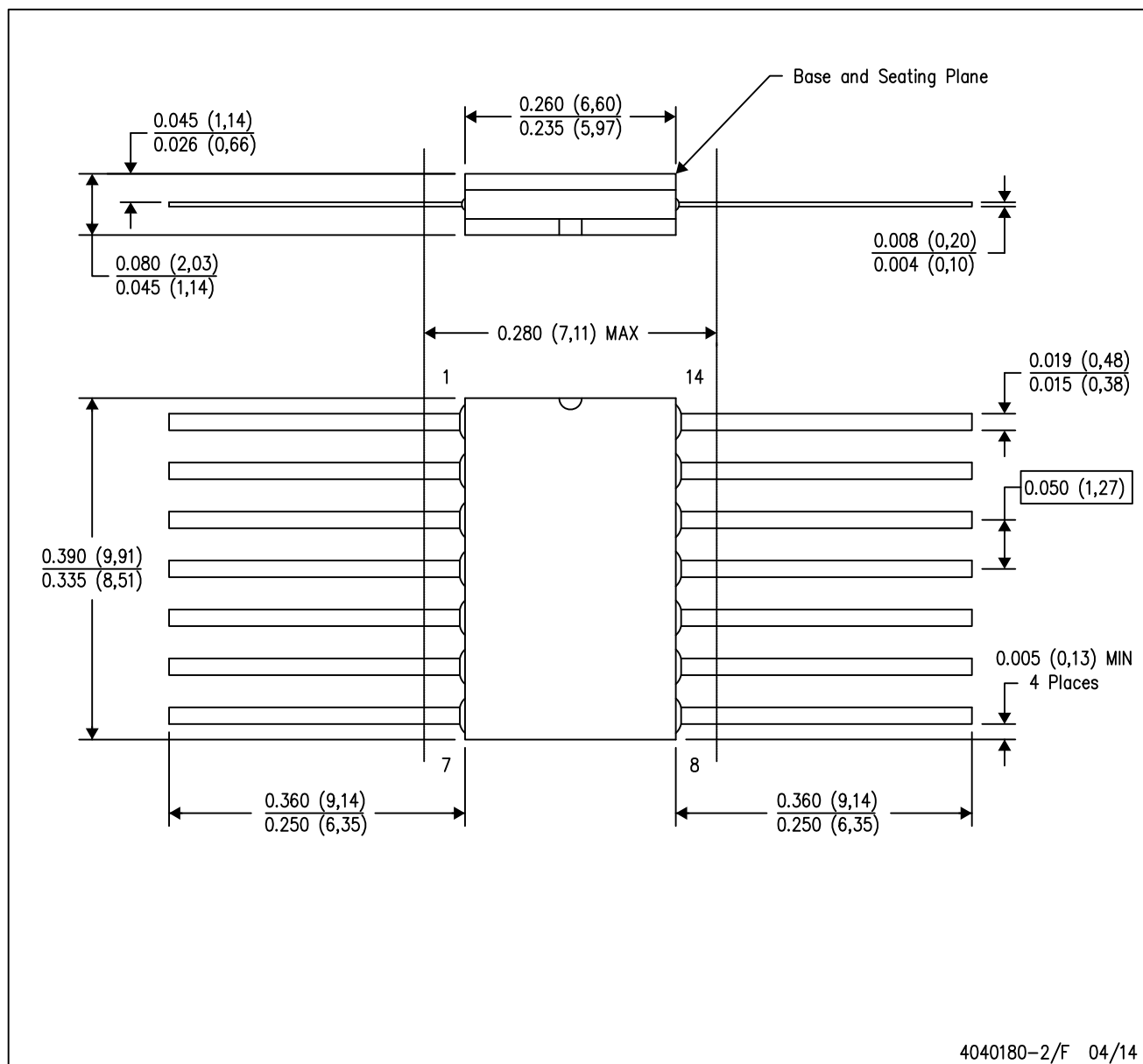


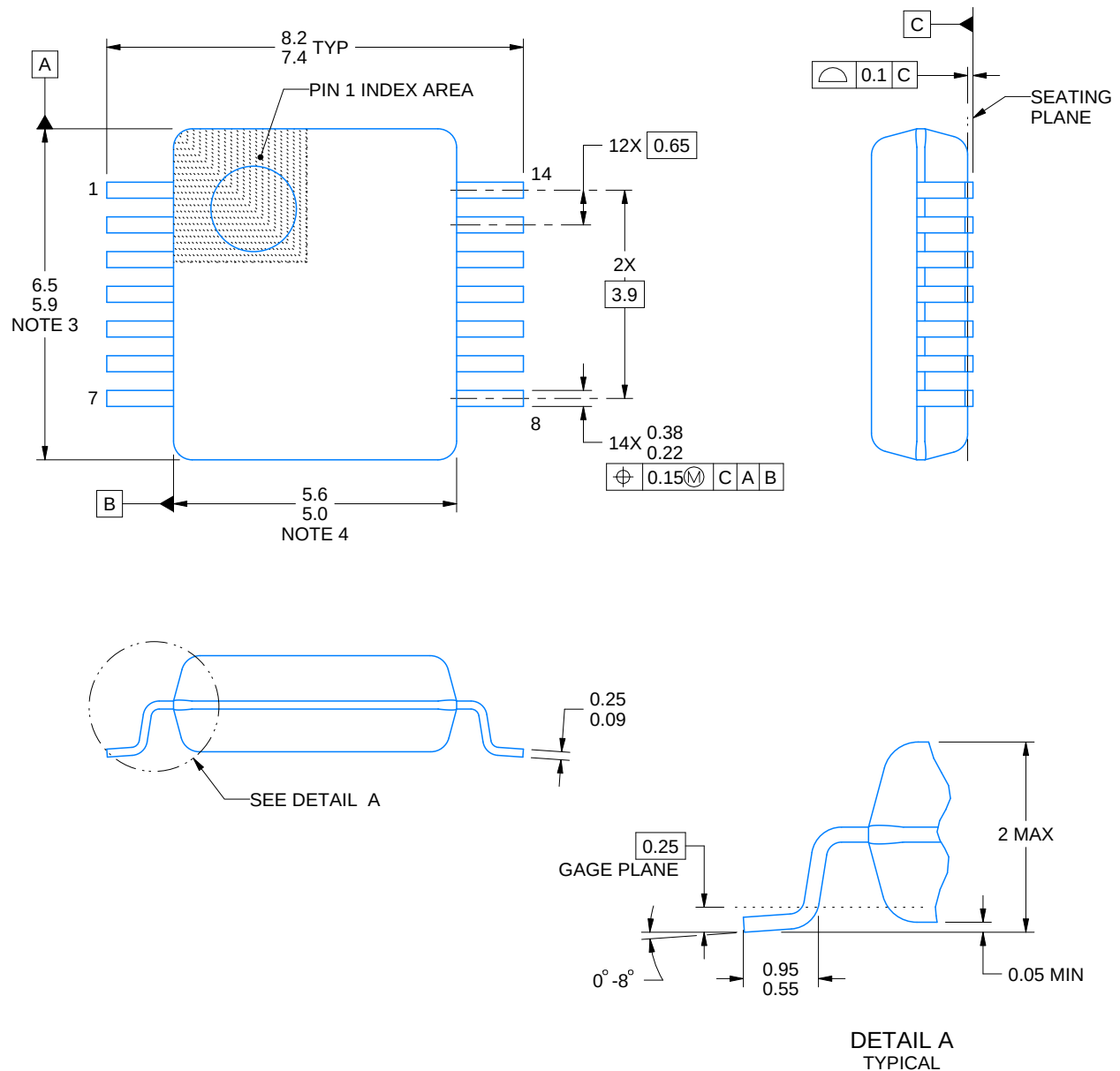
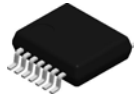
\*All dimensions are nominal

| Device         | Package Name | Package Type | Pins | SPQ | L (mm) | W (mm) | T (μm) | B (mm) |
|----------------|--------------|--------------|------|-----|--------|--------|--------|--------|
| 5962-87609012A | FK           | LCCC         | 20   | 55  | 506.98 | 12.06  | 2030   | NA     |
| 5962-8760901DA | W            | CFP          | 14   | 25  | 506.98 | 26.16  | 6220   | NA     |
| SN74AC04N      | N            | PDIP         | 14   | 25  | 506    | 13.97  | 11230  | 4.32   |
| SN74AC04N      | N            | PDIP         | 14   | 25  | 506    | 13.97  | 11230  | 4.32   |
| SN74AC04N.A    | N            | PDIP         | 14   | 25  | 506    | 13.97  | 11230  | 4.32   |
| SN74AC04N.A    | N            | PDIP         | 14   | 25  | 506    | 13.97  | 11230  | 4.32   |
| SN74AC04NE4    | N            | PDIP         | 14   | 25  | 506    | 13.97  | 11230  | 4.32   |
| SN74AC04NE4    | N            | PDIP         | 14   | 25  | 506    | 13.97  | 11230  | 4.32   |
| SNJ54AC04FK    | FK           | LCCC         | 20   | 55  | 506.98 | 12.06  | 2030   | NA     |
| SNJ54AC04FK.A  | FK           | LCCC         | 20   | 55  | 506.98 | 12.06  | 2030   | NA     |
| SNJ54AC04W     | W            | CFP          | 14   | 25  | 506.98 | 26.16  | 6220   | NA     |
| SNJ54AC04W.A   | W            | CFP          | 14   | 25  | 506.98 | 26.16  | 6220   | NA     |

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK





4220762/A 05/2024

## NOTES:

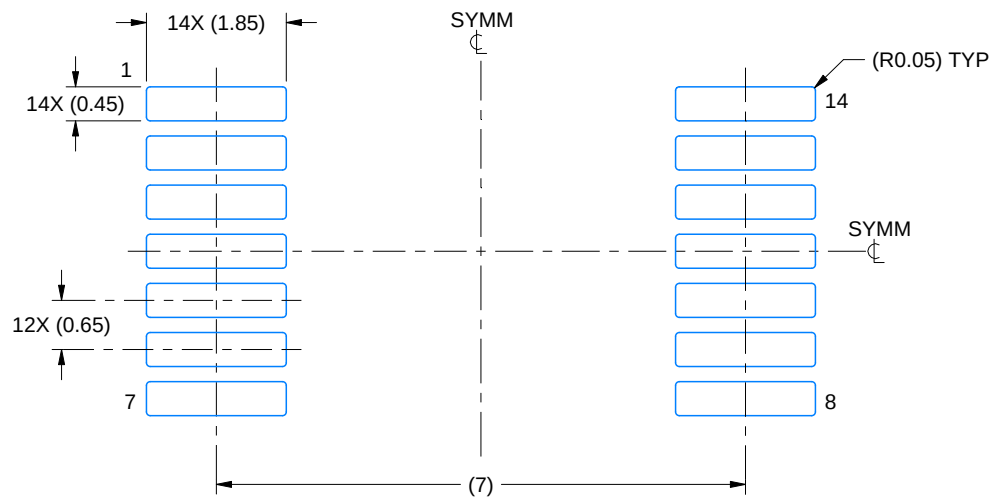
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-150.

# EXAMPLE BOARD LAYOUT

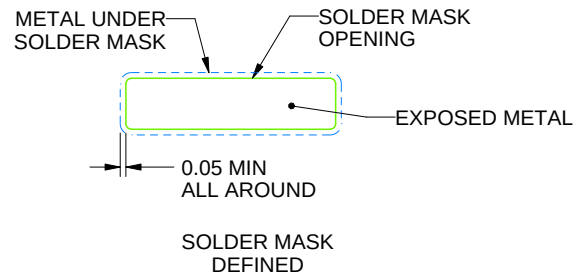
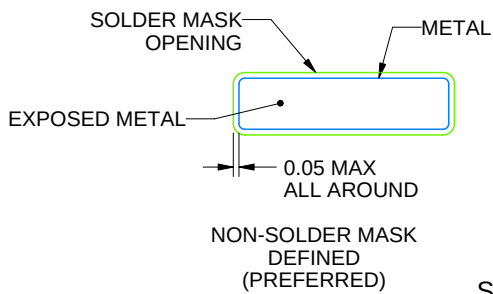
DB0014A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 10X



SOLDER MASK DETAILS

4220762/A 05/2024

NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.

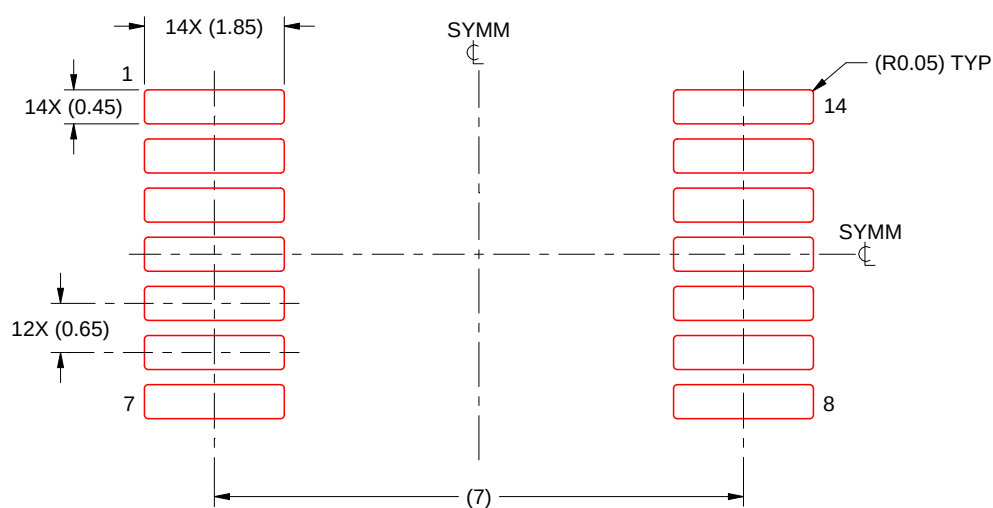
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

DB0014A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE: 10X

4220762/A 05/2024

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

## GENERIC PACKAGE VIEW

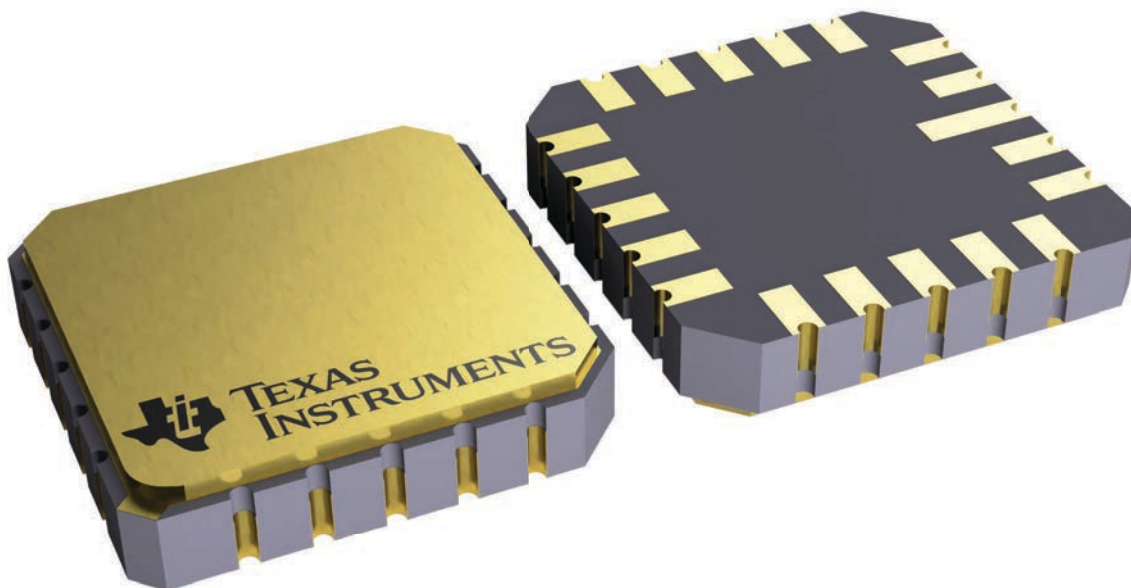
**FK 20**

**LCCC - 2.03 mm max height**

8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.



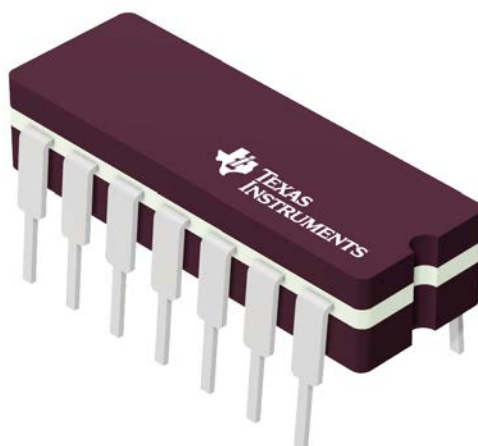
4229370VA\

**J 14**

## GENERIC PACKAGE VIEW

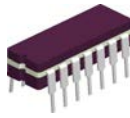
**CDIP - 5.08 mm max height**

CERAMIC DUAL IN LINE PACKAGE

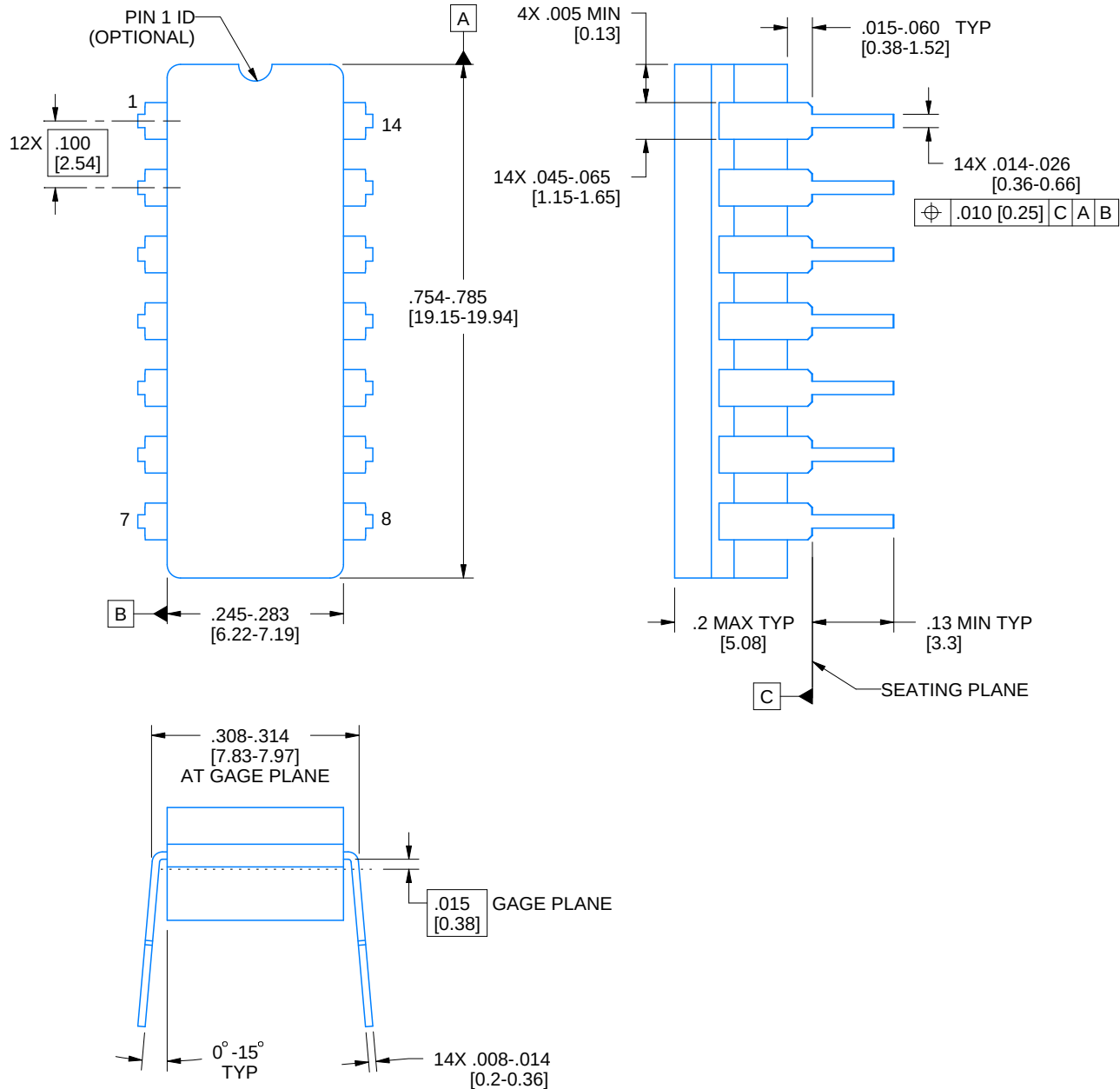


Images above are just a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.

4040083-5/G

**J0014A****PACKAGE OUTLINE****CDIP - 5.08 mm max height**

CERAMIC DUAL IN LINE PACKAGE



4214771/A 05/2017

**NOTES:**

1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This package is hermetically sealed with a ceramic lid using glass frit.
4. Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
5. Falls within MIL-STD-1835 and GDIP1-T14.



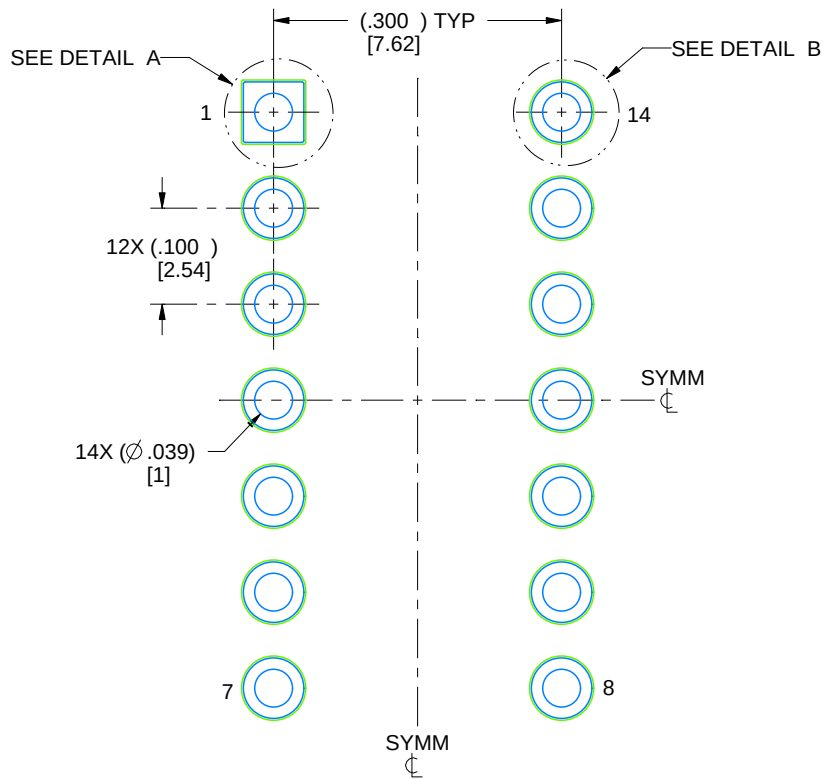
**TEXAS  
INSTRUMENTS**  
www.ti.com

# EXAMPLE BOARD LAYOUT

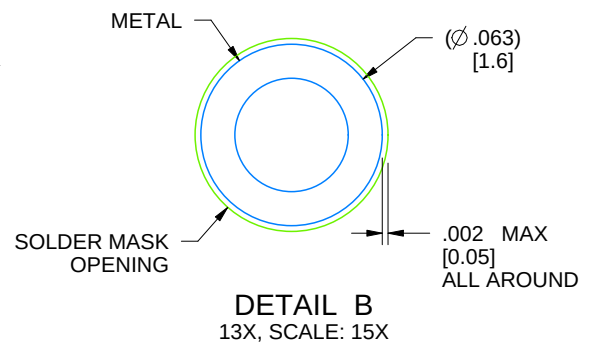
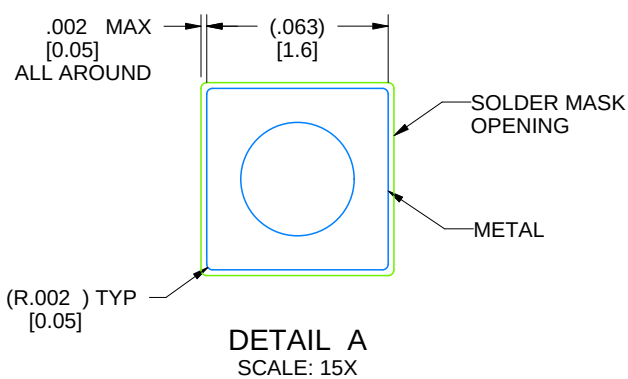
J0014A

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



LAND PATTERN EXAMPLE  
NON-SOLDER MASK DEFINED  
SCALE: 5X

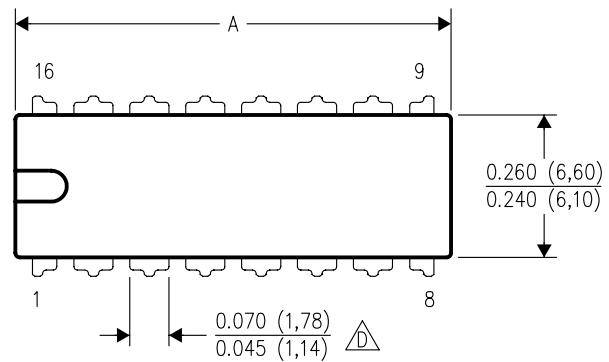


4214771/A 05/2017

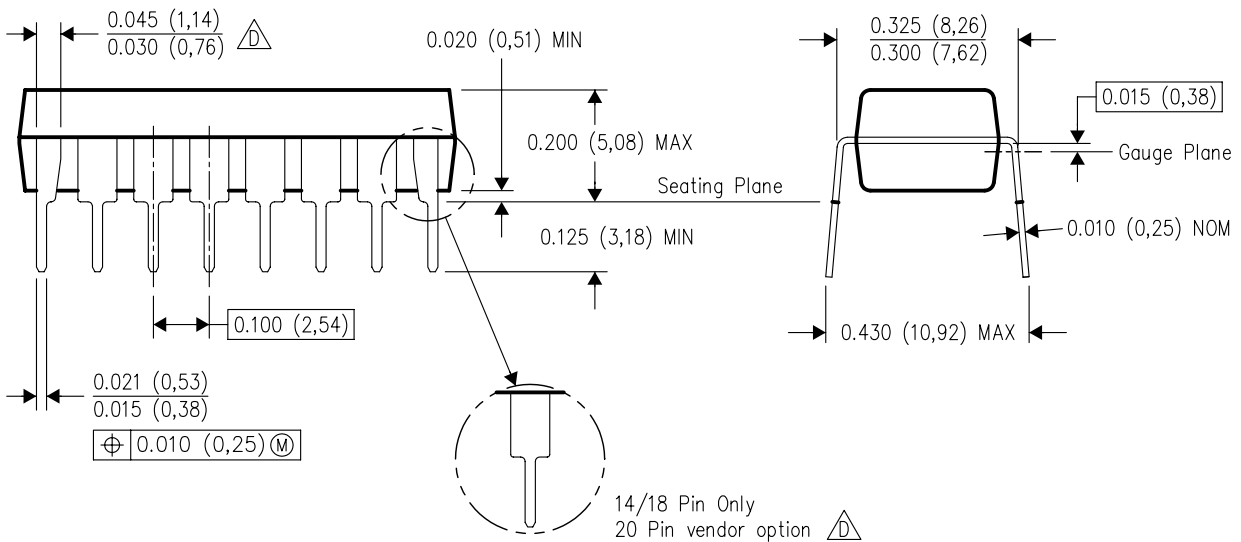
## N (R-PDIP-T\*\*)

16 PINS SHOWN

## PLASTIC DUAL-IN-LINE PACKAGE



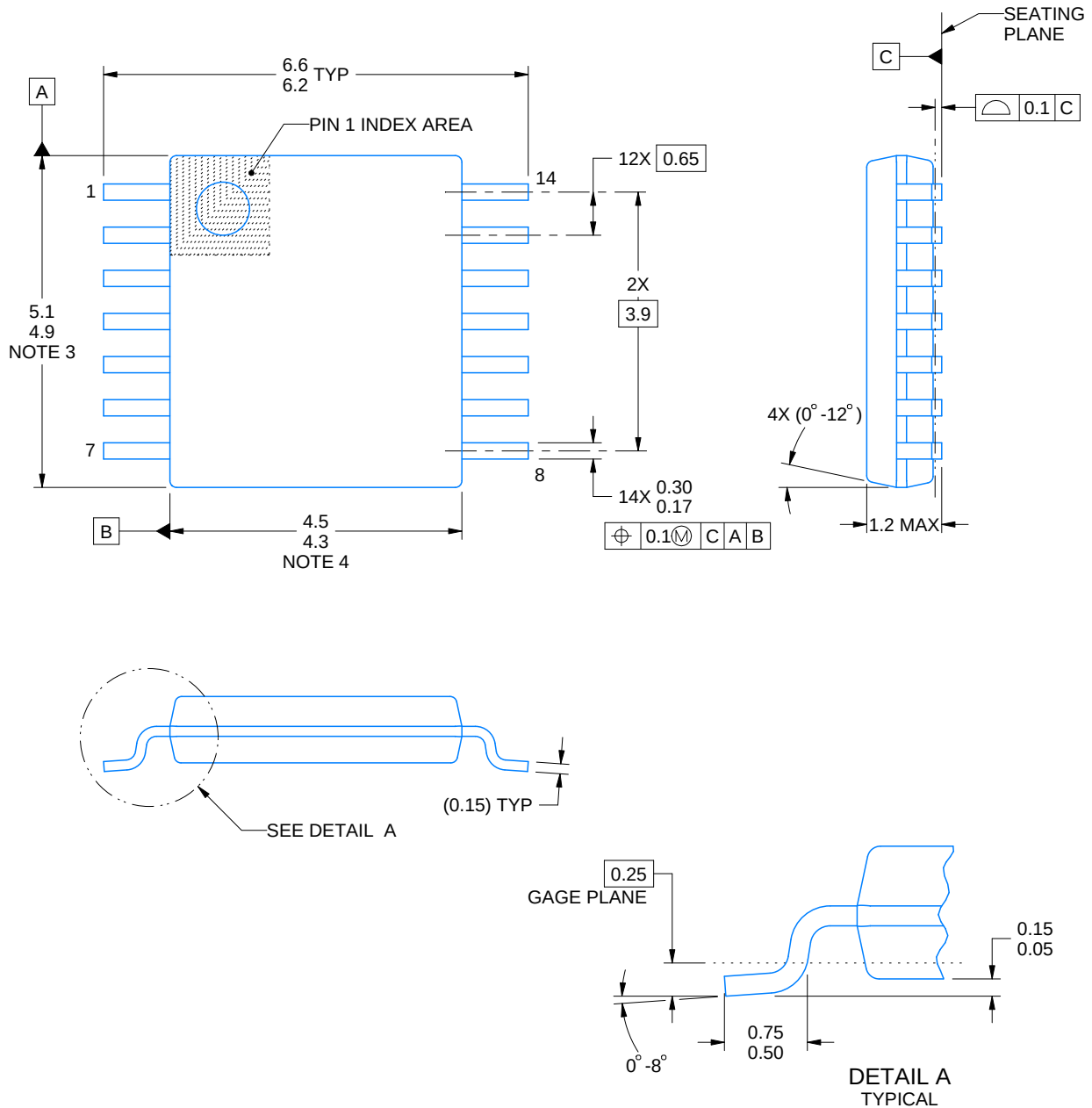
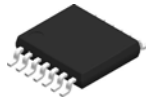
| PINS **             | 14               | 16               | 18               | 20               |
|---------------------|------------------|------------------|------------------|------------------|
| DIM                 |                  |                  |                  |                  |
| A MAX               | 0.775<br>(19,69) | 0.775<br>(19,69) | 0.920<br>(23,37) | 1.060<br>(26,92) |
| A MIN               | 0.745<br>(18,92) | 0.745<br>(18,92) | 0.850<br>(21,59) | 0.940<br>(23,88) |
| MS-001<br>VARIATION | AA               | BB               | AC               | AD               |



14/18 Pin Only  
20 Pin vendor option

4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - The 20 pin end lead shoulder width is a vendor option, either half or full width.



4220202/B 12/2023

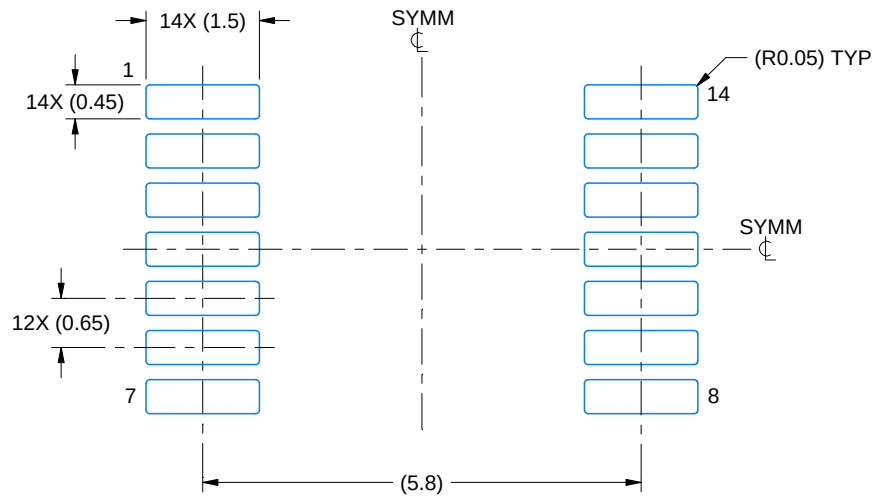
## NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

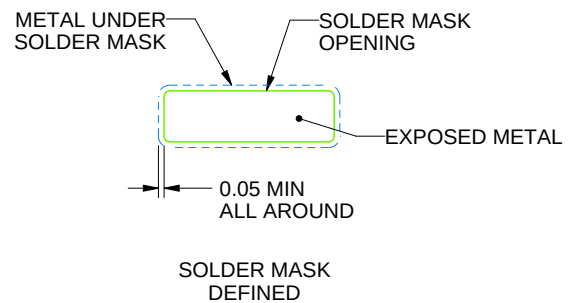
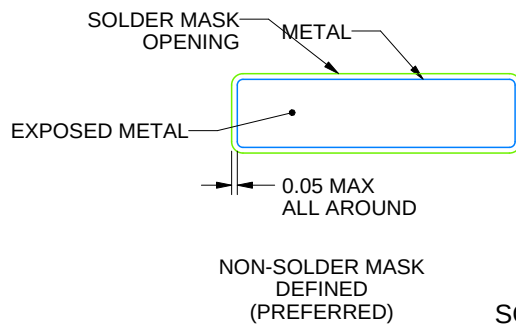
**PW0014A**

**TSSOP - 1.2 mm max height**

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 10X



## SOLDER MASK DETAILS

4220202/B 12/2023

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

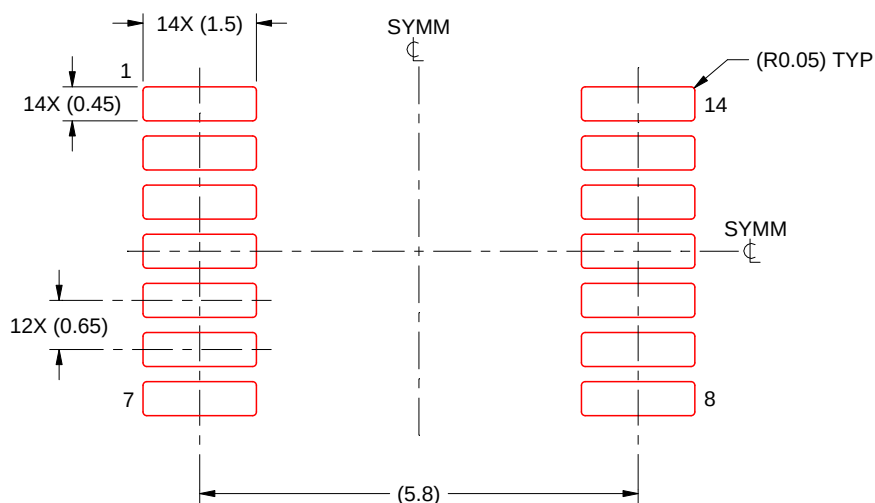
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

PW0014A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE

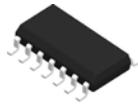


SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE: 10X

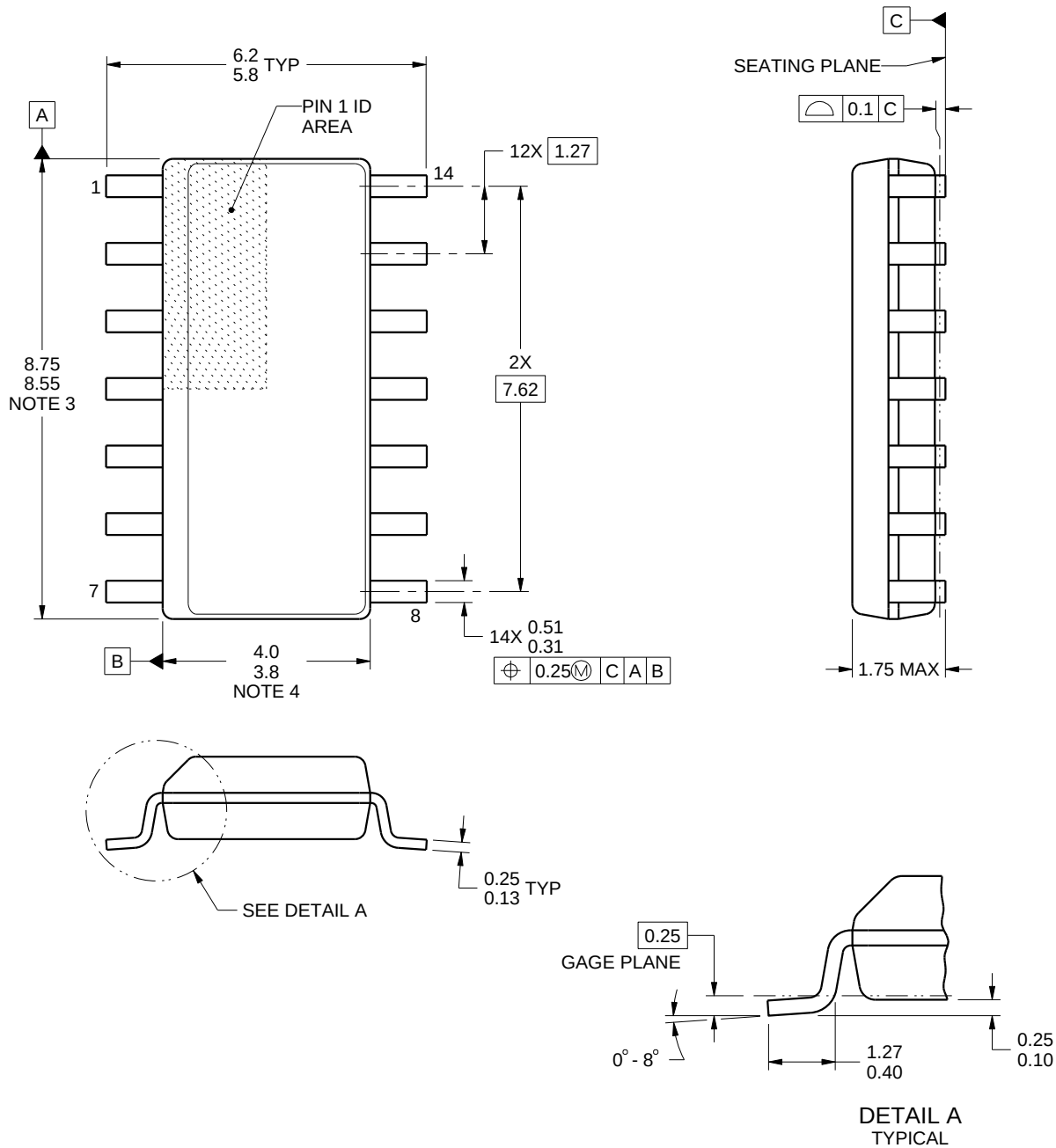
4220202/B 12/2023

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

**D0014A****PACKAGE OUTLINE****SOIC - 1.75 mm max height**

SMALL OUTLINE INTEGRATED CIRCUIT



4220718/A 09/2016

**NOTES:**

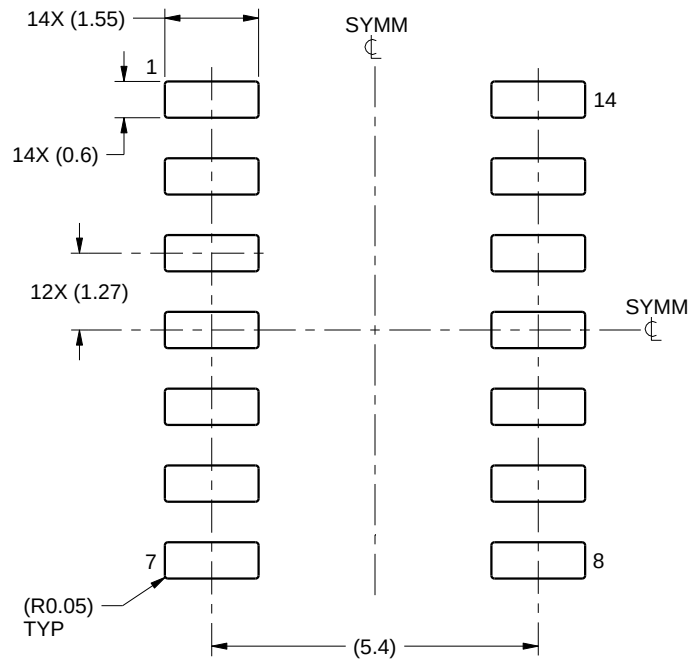
1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
5. Reference JEDEC registration MS-012, variation AB.

# EXAMPLE BOARD LAYOUT

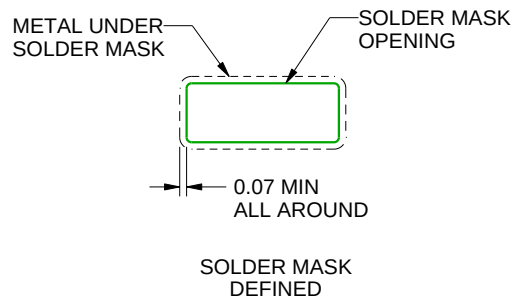
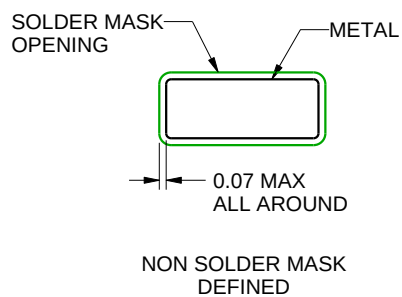
D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



LAND PATTERN EXAMPLE  
SCALE:8X



SOLDER MASK DETAILS

4220718/A 09/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

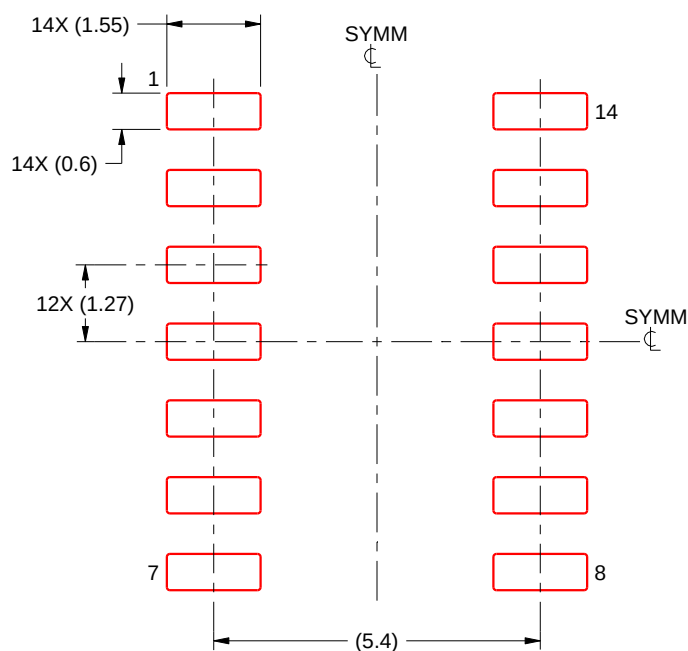
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

## EXAMPLE STENCIL DESIGN

D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:8X

4220718/A 09/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

## GENERIC PACKAGE VIEW

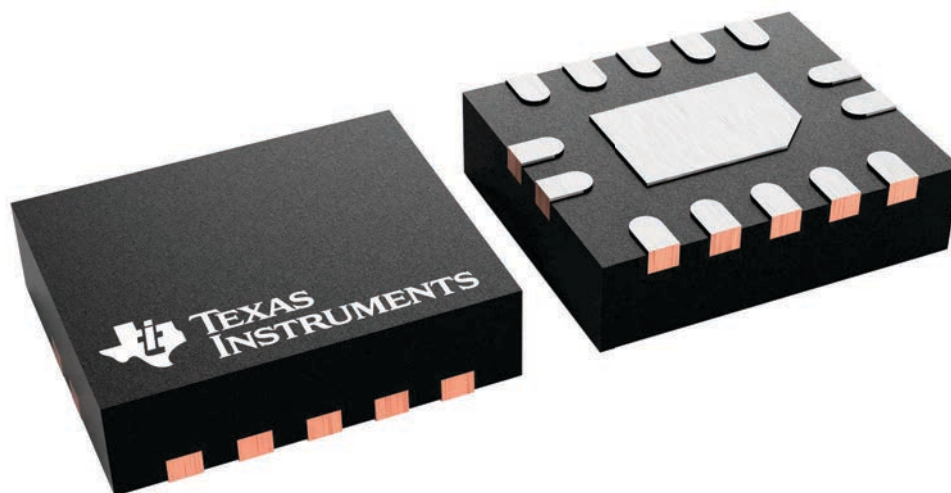
**BQA 14**

**WQFN - 0.8 mm max height**

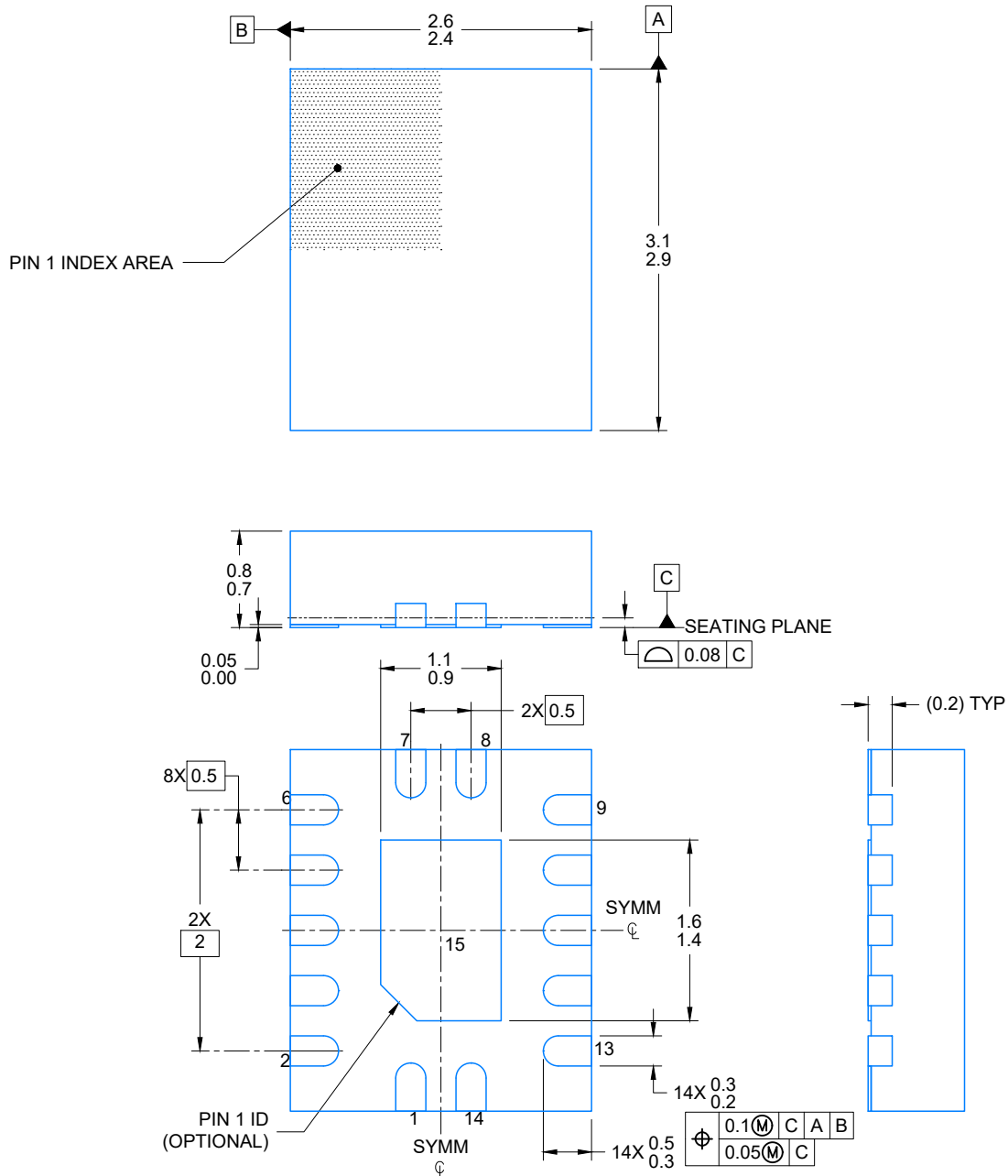
2.5 x 3, 0.5 mm pitch

PLASTIC QUAD FLATPACK - NO LEAD

This image is a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.



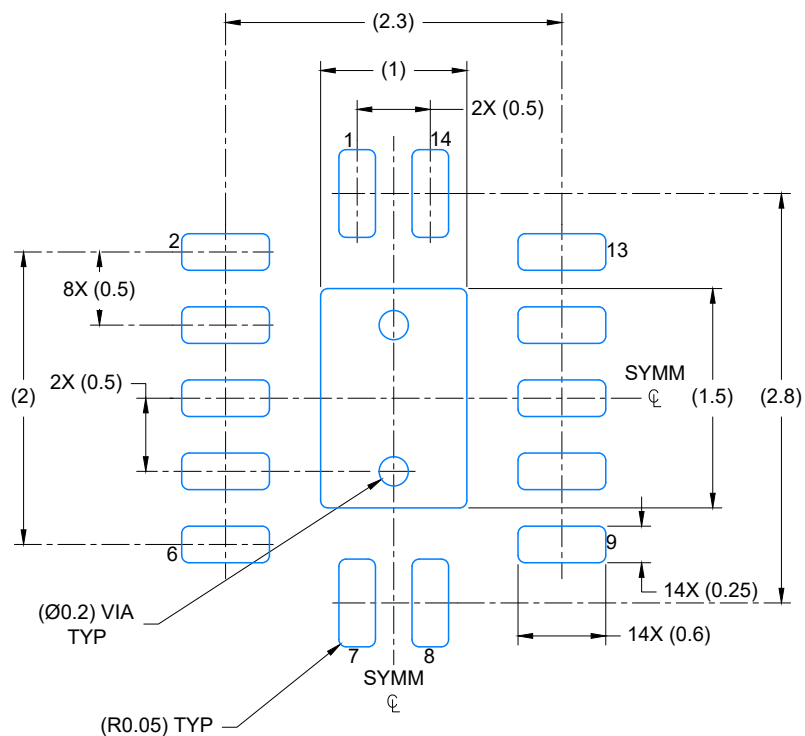
4227145/A



4224636/A 11/2018

## NOTES:

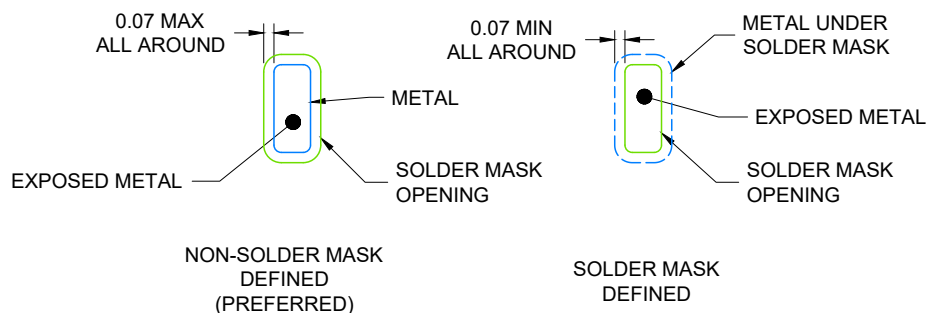
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for optimal thermal and mechanical performance.



## LAND PATTERN EXAMPLE

EXPOSED METAL SHOWN

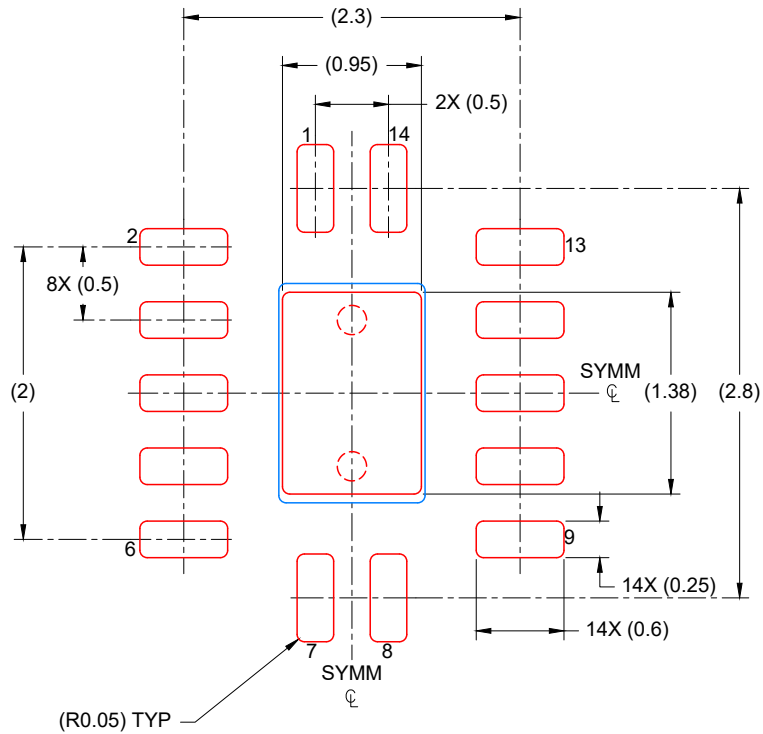
SCALE: 20X



4224636/A 11/2018

## NOTES: (continued)

4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 ([www.ti.com/lit/sluea271](http://www.ti.com/lit/sluea271)).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.



SOLDER PASTE EXAMPLE  
 BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD  
 88% PRINTED COVERAGE BY AREA  
 SCALE: 20X

4224636/A 11/2018

NOTES: (continued)

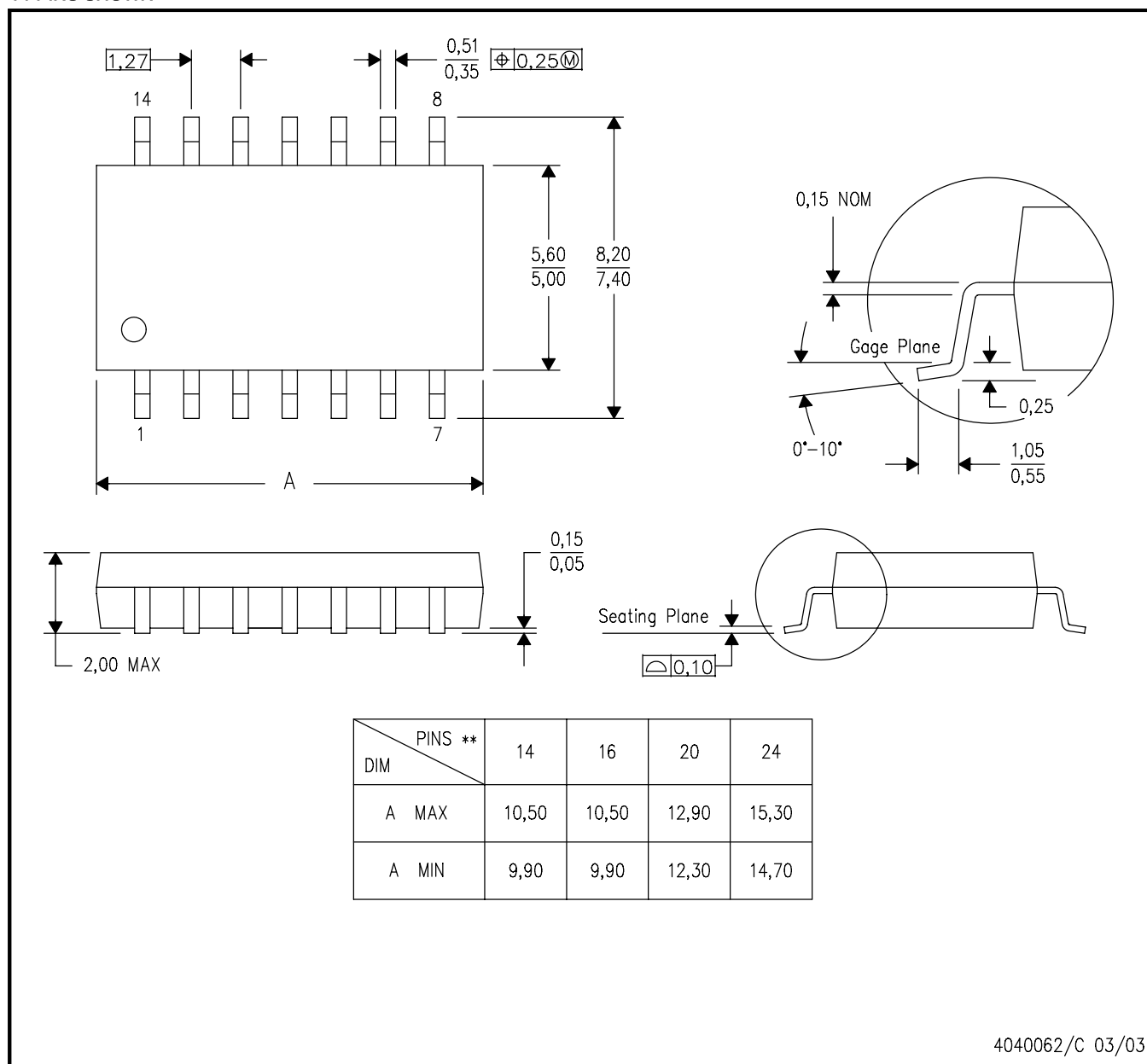
6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

# MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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